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FCPF190N60-F152

N-Channel SuperFET[®] II MOSFET 600 V, 20.2 A, 199 m Ω

Features

- 650 V @T_J = 150°C
- Max. $R_{DS(on)} = 199 \text{ m}\Omega$
- Ultra low gate charge (typ. $Q_g = 57 \text{ nC}$)
- Low effective output capacitance (typ. C_{oss}.eff = 160 pF)
- · 100% avalanche tested

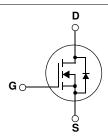
Description

SuperFET®II MOSFET is ON Semiconductor's first generation of high voltage super-junction (SJ) MOSFET family that is utilizing charge balance technology for outstanding low on-resis-tance and lower gate charge performance. This advanced tech-nology is tailored to minimize conduction loss, provide superior switching performance, and withstand extreme dv/dt rate and higher avalanche energy. Consequently, SuperFET®II MOSFET is suitable for various AC/DC power conversion for system minia-turization and higher efficiency.

Aplications

- · LCD / LED / PDP TV Lighting
- · Solar Inverter
- · AC-DC Power Supply





Absolute Maximum Ratings $T_C = 25^{\circ}C$ unless otherwise noted

Symbol		Parameter		FCPF190N60-F152	Unit
V_{DSS}	Drain to Source Voltage			600	V
V	Cata ta Sauraa Valtaga	-DC		±20	V
V_{GSS}	Gate to Source Voltage	-AC	(f >1Hz)	±30	
	Drain Current	-Continuous (T _C = 25°C)		20.2*	A
D	Diam Current	-Continuous (T _C = 100°C)		12.7*	_ ^
I _{DM}	Drain Current	- Pulsed	(Note 1)	60.6*	Α
E _{AS}	Single Pulsed Avalanche En	ergy	(Note 2)	400	mJ
I _{AR}	Avalanche Current		(Note 1)	4.0	Α
E _{AR}	Repetitive Avalanche Energy	,	(Note 1)	2.1	mJ
dv/dt	Peak Diode Recovery dv/dt		(Note 3)	20	V/ns
αν/αι	MOSFET dv/dt			100	V/ns
В	Device Distriction	$(T_C = 25^{\circ}C)$		39	W
P_{D}	Power Dissipation - Derate above 25°C			0.31	W/°C
T _J , T _{STG}	Operating and Storage Temp	erature Range		-55 to +150	°C
T _L	Maximum Lead Temperature 1/8" from Case for 5 Second			300	°C

^{*}Drain current limited by maximum junction temperature

Thermal Characteristics

Symbol	Parameter	FCPF190N60-F152	Unit
$R_{ heta JC}$	Thermal Resistance, Junction to Case	3.2	
$R_{\theta CS}$	Thermal Resistance, Case to Heat Sink (Typical)	0.5	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	62.5	

Package Marking and Ordering Information

Device Marking	Device	Package	Eco Status	Packaging Type	Quantity
FCPF190N60	FCPF190N60-F152	TO-220F	Green 🏈	Tube	50

Electrical Characteristics $T_C = 25^{\circ}C$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
Off Charac	eteristics					
D\/	Drain to Source Breakdown Voltage	$V_{GS} = 0V, I_D = 10mA, T_J = 25^{\circ}C$	600	-	-	V
BV _{DSS}	Drain to Source Breakdown Voltage	$V_{GS} = 0V, I_D = 10mA, T_J = 150^{\circ}C$	650	-	-	V
$\frac{\Delta BV_{DSS}}{\Delta T_J}$	Breakdown Voltage Temperature Coefficient	I _D = 10mA, Referenced to 25°C	-	0.67	-	V/°C
BV _{DS}	Drain-Source Avalanche Breakdown Voltage	$V_{GS} = 0V, I_D = 20A$	-	700	-	V
ı	Zara Cata Valtaga Drain Current	V _{DS} = 480V, V _{GS} = 0V	-	-	10	^
I _{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 480V, T_{C} = 125^{\circ}C$	-	-	10	μА
I _{GSS}	Gate to Body Leakage Current	$V_{GS} = \pm 20V, V_{DS} = 0V$	-	-	±100	nA

On Characteristics

V _{GS(th)}	Gate Threshold Voltage	$V_{GS} = V_{DS}, I_D = 250 \mu A$	2.5	-	3.5	V
R _{DS(on)}	Static Drain to Source On Resistance	$V_{GS} = 10V, I_D = 10A$	-	0.17	0.199	Ω
9 _{FS}	Forward Transconductance	$V_{DS} = 20V, I_{D} = 10A$	-	21	-	S

Dynamic Characteristics

C _{iss}	Input Capacitance	V 05V V 0V	-	2220	2950	pF
C _{oss}	Output Capacitance	V _{DS} = 25V, V _{GS} = 0V f = 1MHz	-	1630	2165	pF
C _{rss}	Reverse Transfer Capacitance	1 - 1101112	-	85	128	pF
C _{oss}	Output Capacitance	$V_{DS} = 380V, V_{GS} = 0V, f = 1MHz$	-	42	-	pF
C _{oss} eff.	Effective Output Capacitance	$V_{DS} = 0V$ to 480V, $V_{GS} = 0V$	-	160	-	pF
Q _{g(tot)}	Total Gate Charge at 10V	V _{DS} = 380V, I _D = 10A	-	57	74	nC
Q_{gs}	Gate to Source Gate Charge	V _{GS} = 10V	-	9	-	nC
Q_{gd}	Gate to Drain "Miller" Charge	(Note 4)	-	21	-	nC
ESR	Equivalent Series Resistance	f = 1MHz	-	1	-	Ω

Switching Characteristics

t _{d(on)}	Turn-On Delay Time			-	20	50	ns
t _r	Turn-On Rise Time	$V_{DD} = 380V, I_{D} = 10A$		-	10	30	ns
t _{d(off)}	Turn-Off Delay Time	$V_{GS} = 10V, R_g = 4.7\Omega$		-	64	138	ns
t _f	Turn-Off Fall Time		(Note 4)	-	5	20	ns

Drain-Source Diode Characteristics

I _S	Maximum Continuous Drain to Source Diode Forward Current			-	20.2	Α
I _{SM}	Maximum Pulsed Drain to Source Diode Forward Current			-	60.6	Α
V_{SD}	Drain to Source Diode Forward Voltage V _{GS} = 0V, I _{SD} = 10A		-	-	1.2	V
t _{rr}	Reverse Recovery Time	$V_{GS} = 0V, I_{SD} = 10A$	-	280	-	ns
Q _{rr}	Reverse Recovery Charge	$dI_F/dt = 100A/\mu s$	-	3.8	-	μС

Notes

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature
- 2. I_{AS} = 4A, V_{DD} = 50V, R_{G} = 25\Omega, Starting T_{J} = 25^{\circ}C
- 3. $I_{SD} \le 10 \text{A}$, di/dt $\le 200 \text{A}/\mu\text{s}$, $V_{DD} \le BV_{DSS}$, Starting $T_J = 25^{\circ}\text{C}$
- 4. Essentially Independent of Operating Temperature Typical Characteristics

Typical Performance Characteristics

Figure 1. On-Region Characteristics

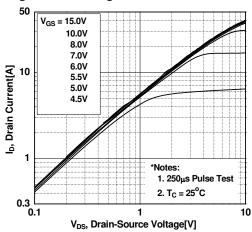


Figure 3. On-Resistance Variation vs.

Drain Current and Gate Voltage

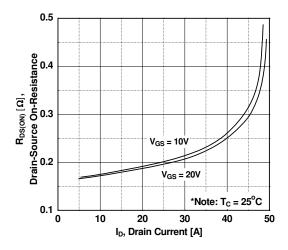


Figure 5. Capacitance Characteristics

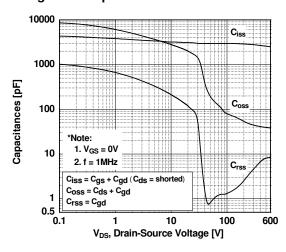


Figure 2. Transfer Characteristics

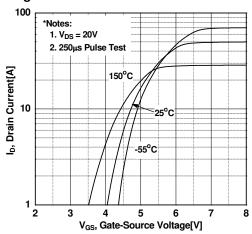


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

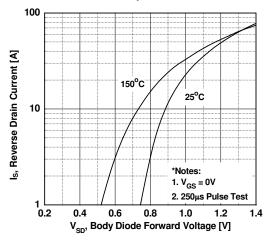
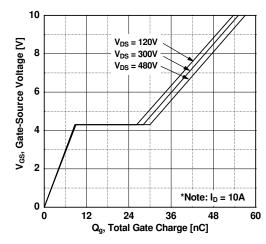


Figure 6. Gate Charge Characteristics



Typical Performance Characteristics (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

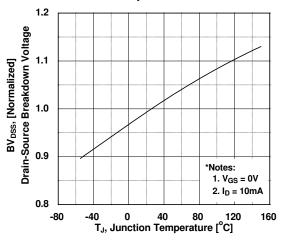


Figure 9. Maximum Safe Operating Area vs. Case Temperature

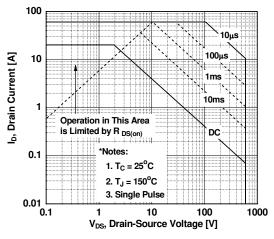


Figure 11. Maximum Drain Current

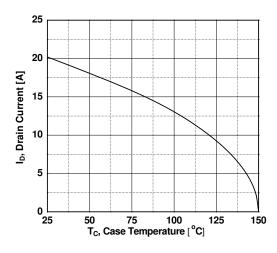


Figure 8. On-Resistance Variation vs. Temperature

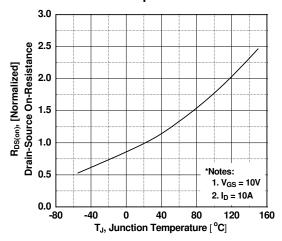
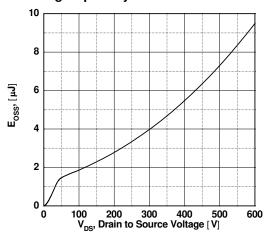
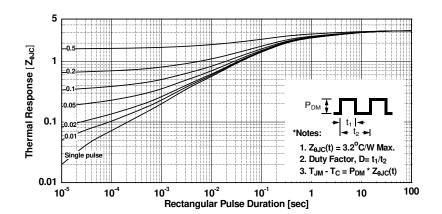


Figure 10. Eoss vs. Drain to Source Voltage Switching Capability

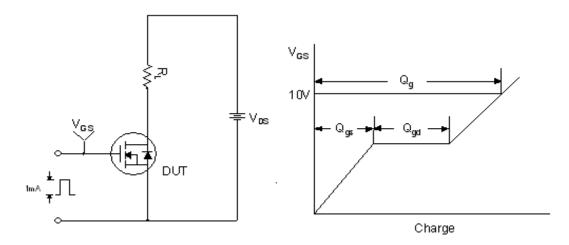


Typical Performance Characteristics (Continued)

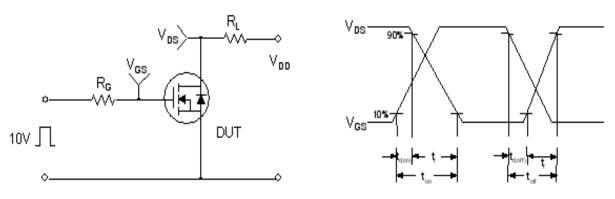
Figure 12. Transient Thermal Response Curve



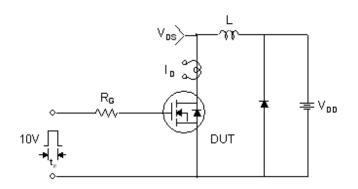
Gate Charge Test Circuit & Waveform

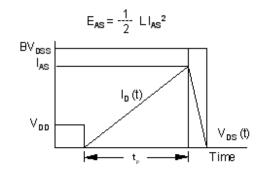


Resistive Switching Test Circuit & Waveforms

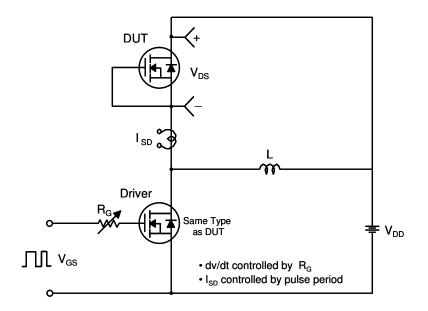


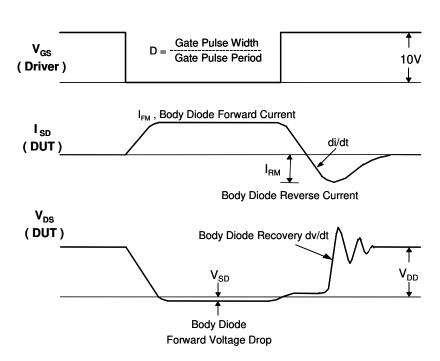
Unclamped Inductive Switching Test Circuit & Waveforms





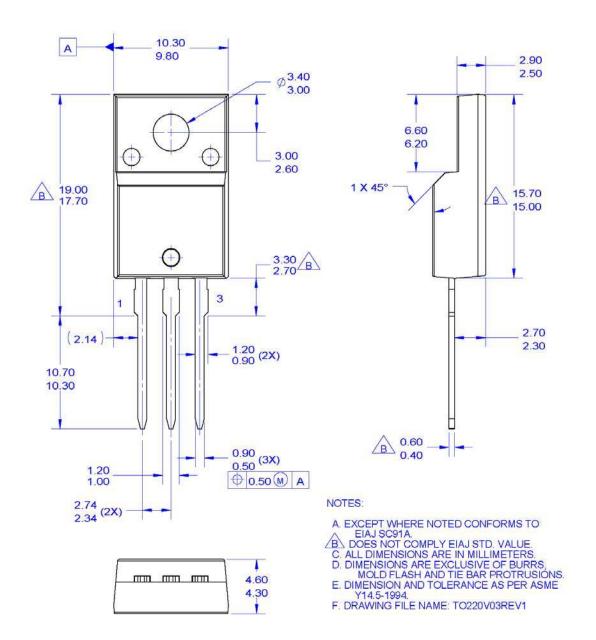
Peak Diode Recovery dv/dt Test Circuit & Waveforms





Mechanical Dimensions

TO-220F



* Front/Back Side Isolation Voltage : AC 2500V

TO-220, MOLDED, 3LD, FULL PACK, EIAJ SC91

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